## **CLAIMS**

1. A sealant for liquid crystals comprising as essential ingredients (a) a radiation curable resin represented by the general formula (1):

$$\begin{array}{c|c}
R^{3} & O & OH \\
\hline
0 & R^{1} & O & R^{2} \\
\hline
0 & R^{2} & R^{2} \\
\hline
0 & R^{2} & R^{2} \\
\hline
\end{array}$$
(1)

wherein  $R^1$  represents a hydrogen atom or a methyl group,  $R^2$  represents a hydrogen atom, a halogen atom, a hydroxyl group, a linear, branch or cyclic monovalent alkyl group having 1 to 10 carbon atoms, or an alkoxy group having 1 to 10 carbon atoms, m represents an integer of 1 to 4, and may be the same or different,  $R^3$  represents a hydrogen atom or a methyl group, and the number n of the repeating units is a positive number in the range of 0 to 20; (b) a photopolymerization initiator; and (c) an inorganic filler having an average particle diameter of 3  $\mu$ m or less.

2. The sealant for liquid crystals according to claim 1, wherein the radiation curable resin (a) is a radiation curable resin represented by the general formula (2):

wherein the number p of the repeating units is a positive number in the range of 0 to 20.

- 3. The sealant for liquid crystals according to claim 1 or 2, wherein the radiation curable resin (a) has a content of 30% by weight to 80% by weight based on the total amount of the sealant for liquid crystals.
- 4. The sealant for liquid crystals according to any one of claims 1 to 3, wherein the radiation curable resin (a) has a viscosity of 30 to 500 Pa·s.
- 5. The sealant for liquid crystals according to any one of claims 1 to 4, wherein the photopolymerization initiator (b) is a radical type photopolymerization initiator.
- 6. The sealant for liquid crystals according to claim 5 wherein the radical type photopolymerization initiator (b) is a carbazole initiator.
- 7. The sealant for liquid crystals according to any one of claims 1 to 6, further comprising (d) an epoxy resin and (e) a heat-curing agent.
- 8. The sealant for liquid crystals according to claim 7, wherein the epoxy resin (d) is an epoxy resin which does not elute into the liquid crystals in an amount of 0.5% by weight or more based on the liquid crystals when the epoxy resin is brought directly into contact with the liquid crystals whose amount is 10 times of the epoxy resin and is allowed to stand at 120°C for 1 hour.

- 9. The sealant for liquid crystals according to claim 7 or 8, wherein the heat-curing agent (e) is a dihydrazide.
- 10. The sealant for liquid crystals according to claim 9, wherein the dihydrazide is a dihydrazide having a skeleton of isophthalic dihydrazide and/or valine hydantoin.
- 11. The sealant for liquid crystals according to claim 7 or 8, wherein the heat-curing agent(e) is a polyhydric phenol.
- 12. The sealant for liquid crystals according to any one of claims 1 to 11, further comprising (f) a silane coupling agent.
- 13. The sealant for liquid crystals according to claim 12, wherein the silane coupling agent is a silane coupling agent having an amino group.
- 14. A liquid crystal display cell which is sealed with a cured product of a sealant for liquid crystals according to any one of claims 1 to 13.
- 15. A process for producing a liquid crystal display cell comprising dropping liquid crystals inside a sealant for liquid crystals according to any one of claims 1 to 13 formed on a substrate and attaching another substrate thereto.